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8 October 2013

Ms. Susanna Kooistra
Mr. Patrick Merias
ETSI, MCC
650, route des Lucioles
Sophia-Antipolis
France

Subject: Nomination of candidate for the 3GPP TSG RAN5 Vice Chairman

Dear Ms. Kooistra and Mr. Merias:

I am pleased to inform you that Qualcomm, through its ATIS 3GPP affiliation, is nominating Mr. Pradeep Gowda as a candidate for the position of 3GPP TSG RAN5 Vice Chairman at the upcoming election in RAN5#61. If Pradeep is elected, Qualcomm will fully support him in his RAN5 leadership role.

In proposing Pradeep Gowda for the position of 3GPP TSG RAN5 Vice Chairman, Qualcomm remains fully committed to the success of 3GPP and its diverse ecosystem.

A brief curriculum vitae of Pradeep Gowda is attached.

Best Regards,

Edward G. Tiedemann Jr.

Edward G. Tiedemann, Jr.
Senior Vice-President, Engineering
QUALCOMM Technologies, Inc.

Pradeep Gowda

Pradeep has been working at QUALCOMM since 2001 and has been involved in RF and Layer1 conformance testing of LTE, CDMA2000, WCDMA and GERAN chipsets. For the last 10 years he has been leading RF and Layer1 system testing activities, and coordinating and planning Layer1 and RF verification activities with cross functional teams (involving Systems, SW and HW engineers).

In November 2008, Pradeep started attending RAN WG5 meetings. For the past five years, he has been actively contributing to RF and Layer1 aspects of HSPA, DC-HSDPA, and LTE specifications. During his time as a RAN5 RF delegate, he actively contributed and enabled the completion of several RAN5 Work items namely HSPA Type3i, LTE Rel8, LTE CA Rel9/10 (multiple band combos), LTE eICIC, and LTE application layer data throughput. Pradeep also led the 3GPP RAN5 RF subgroup as a Vice Chair for one RAN5 WG meeting.

Pradeep graduated in 2001 with a Master's degree in Electrical Engineering from State University of New York Buffalo, USA.